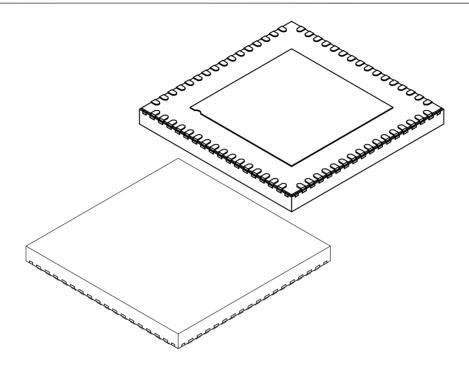
64-Lead Very Thin Quad Flat, No Lead Package (LZX) - 9x9x0.9 mm Body [VQFN] With 6.00 mm Exposed Pad and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	64		
Pitch	е	0.50 BSC		
Overall Height	Α	1	_	0.90
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.203 REF		
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	5.90	6.00	6.10
Overall Width	Е	9.00 BSC		
Exposed Pad Width	E2	5.90	6.00	6.10
Terminal Width	b	0.18	0.25	0.30
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	1.10 REF		
Wettable Flank Step Length	D3	-	-	0.085
Wettable Flank Step Height	A4	0.10	-	0.19

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.